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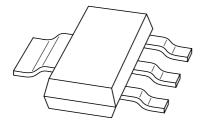
If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

DISCRETE SEMICONDUCTORS

DATA SHEET



PZTA44NPN high-voltage transistor

Product data sheet Supersedes data of 1998 Nov 26 1999 May 21



NPN high-voltage transistor

PZTA44

FEATURES

- Low current (max. 300 mA)
- High voltage (max. 400 V).

APPLICATIONS

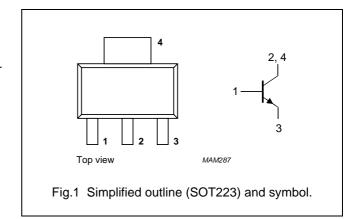
• Telecommunication.

DESCRIPTION

NPN high-voltage transistor in a SOT223 plastic package.

PINNING

PIN	DESCRIPTION	
1	base	
2, 4	collector	
3	emitter	



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	500	V
V _{CEO}	collector-emitter voltage	open base	_	400	V
V _{EBO}	emitter-base voltage	open collector	_	6	V
I _C	collector current (DC)		_	300	mA
I _{CM}	peak collector current		_	300	mA
I _{BM}	peak base current		-	100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	1.35	W
T _{stg}	storage temperature		-65	+150	°C
T _j	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Note

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm². For other mounting conditions, see *"Thermal considerations for SOT223 in the General Part of associated Handbook"*.

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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	note 1	91	K/W
R _{th j-s}	thermal resistance from junction to soldering point		10	K/W

Note

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm². For other mounting conditions, see *"Thermal considerations for SOT223 in the General Part of associated Handbook"*.

CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER CONDITIONS		MIN.	MAX.	UNIT
I _{CBO}	collector cut-off current	I _E = 0; V _{CB} = 400 V	_	100	nA
		I _E = 0; V _{CB} = 400 V; T _j = 150 °C	_	10	μΑ
I _{EBO}	emitter cut-off current	I _C = 0; V _{EB} = 4 V	_	100	nA
h _{FE}	DC current gain	V _{CE} = 10 V			
		$I_C = 1 \text{ mA}$	40	_	
		I _C = 10 mA	50	200	
		I _C = 50 mA; note 1	45	_	
		I _C = 100 mA; note 1	40	_	
V _{CEsat}	collector-emitter saturation voltage	I _C = 1 mA; I _B = 0.1 mA	_	400	mV
		I _C = 10 mA; I _B = 1 mA	_	500	mV
		I _C = 50 mA; I _B = 5 mA; note 1	_	750	mV
V _{BEsat}	base-emitter saturation voltage	$I_C = 10 \text{ mA}; I_B = 1 \text{ mA}; \text{ note 1}$	_	850	mV
C _c	collector capacitance	$I_E = i_e = 0$; $V_{CB} = 20 \text{ V}$; $f = 1 \text{ MHz}$	_	7	pF
C _e	emitter capacitance	$I_C = I_c = 0$; $V_{EB} = 500 \text{ mV}$; $f = 1 \text{ MHz}$	_	180	pF
f _T	transition frequency	I _C = 10 mA; V _{CE} = 10 V; f = 100 MHz	20	_	MHz

Note

1. Pulse test: $t_p \le 300~\mu s;~\delta \le 0.02.$

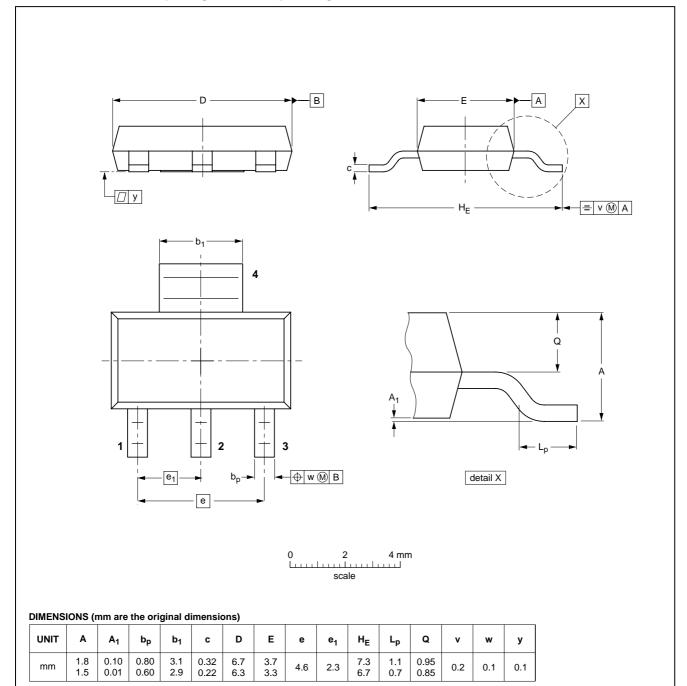
NPN high-voltage transistor

PZTA44

PACKAGE OUTLINE

Plastic surface mounted package; collector pad for good heat transfer; 4 leads

SOT223



OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1330E DATE
SOT223			SC-73			97-02-28 99-09-13

NPN high-voltage transistor

PZTA44

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

For additional information please visit: http://www.nxp.com
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